

Session HH

Microwave and Millimeter-wave Packaging



Chairman:

Bert Berson

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In this session we will present advances in three major areas: component and multi-chip packages, interconnects, and assembly. The frequency range covered is from L band through Ka band. The papers cover device, component, and subsystem packaging. The topics covered include: a low cost approach to high levels of integration, the use of quartz for high frequency packaging, new microstrip structures in polyimide, use of constant length wire bonds to minimize the effect of placement errors, and a discussion of reliability effects of thermal expansion mismatch of GaAs to diverse base materials.

**10:30 a.m.–12:00 p.m., Thursday, June 13, 1991
Ballroom B**